



# 100% Material Declaration Data Sheet BG352

PK195 (v1.0.1) January 8, 2007

Material Declaration Data Sheet

**Average Weight: 7.142g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.0291</b>	<b>0.41%</b>
	Silicon	7440-21-3	100.00		0.0291	
<b>Die Attach Material</b>					<b>0.004</b>	<b>0.06%</b>
	Resin	Trade Secret	25.00		0.001	
	Silver	7440-22-4	75.00		0.003	
<b>Mold Compound</b>					<b>0.2374</b>	<b>3.32%</b>
	Resin	Trade Secret	26.00		0.062	
	Silica	60676-86-0	74.00		0.176	
<b>Dam</b>					<b>0.0088</b>	<b>0.12%</b>
	Proprietary	Trade Secret	27.00			
	Silica	60676-86-0	73.00			
<b>Laminate</b>					<b>0.647</b>	<b>9.06%</b>
	Copper	7440-50-8		Metal Layer	0.101	
	Nickel	7440-02-0		Metal Layer	0.006	
	Gold	7440-57-5		Metal Layer	0.002	
	Board	Trade Secret			0.396	
	Solder Mask (EP)	Trade Secret			0.142	
<b>Heat Sink</b>					<b>5.252</b>	<b>73.54%</b>
	Copper	7440-50-8	100.00		5.252	
<b>Heat Sink Plating</b>					<b>0.2243</b>	<b>3.14%</b>
	Nickel	7440-02-0	100.00		0.2243	
<b>Gold Wire</b>					<b>0.0224</b>	<b>0.31%</b>
	Gold	7440-57-5	100.00		0.0224	
<b>Solder Balls</b>					<b>0.717</b>	<b>10.04%</b>
	Tin	7440-31-5	63.00		0.452	
	Lead	7439-92-1	37.00		0.265	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/5/06	1.0	Initial release.
1/8/07	1.0.1	Corrected Gold Wire CAS# entry.